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**Amendments to the Claims**

Amend Claims 1, 3, and 6 and add a new Claim 11 as follows:

1. (Currently Amended) A method of forming a hole in a board, comprising the steps of:

- (a) irradiating a laser beam on a surface of said board from a direction perpendicular thereto to thereby drill a hole in said board;
- (b) irradiating a laser beam onto said hole from a direction inclined at a predetermined angle relative to said perpendicular direction; and
- (c) repeating the step (b) until diameters of a top portion and a bottom portion of said hole become substantially equal to each other and the sides of said hole are substantially parallel.

2. (Original) The method according to claim 1, wherein said predetermined angle is selected within the range of from about 2 to 5 degrees measured from a perpendicular direction relative to said board.

3. (Currently Amended) A method of forming a plurality of holes in a board, comprising the steps of:

- (a) irradiating a laser beam on a surface of said board from a direction perpendicular thereto in a plurality of predetermined positions thereof in turn to thereby drill a plurality of holes in said board;
- (b) irradiating a laser beam onto the holes drilled in said plurality of predetermined positions in turn from a direction inclined at a predetermined angle relative to said perpendicular direction; and
- (c) repeating the step (b) until diameters of a top portion and a bottom portion of each of said holes become substantially equal to each other and the sides of each of said holes are substantially parallel.

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4. (Original) The method according to claim 3, wherein said predetermined angle is selected within the range of from about 2 to 5 degrees measured from a perpendicular direction relative to said board.

5. (Original) The method according to claim 4, wherein the step (c) repeating the step (b) includes a step of irradiating a laser beam while changing a laser beam irradiation position along a circumferential direction of each of said holes.

6. (Currently Amended) A method of forming a plurality of holes in a board, comprising the steps of:

(a) irradiating a laser beam on a surface of said board from a direction inclined at a predetermined angle relative to a direction perpendicular to the surface of said board, in a plurality of predetermined positions of said board in turn to thereby drill a plurality of holes in said board; and

(b) repeating the step (a) until diameters of a top portion and a bottom portion of each of said holes become substantially equal to each other and the sides of each of said holes are substantially parallel.

7. (Original) The method according to claim 6, wherein said predetermined angle is selected within the range of from about 2 to 5 degrees measured from a perpendicular direction relative to said board.

8. (Original) The method according to claim 7, wherein the step (b) repeating the step (a) includes a step of irradiating a laser beam while changing a laser beam irradiation position along a circumferential direction of each of said holes.

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9. (Original) A hole drilling apparatus comprising:
- an oscillator producing a laser beam for drilling a hole in a board;
  - a lens through which the laser beam passes and which determines an angle of the laser beam relative to said board depending on a laser beam passing position of said lens;
  - a mirror changing the laser beam passing position of said lens depending on the number of times of laser beam irradiation to said board;
  - a mask having the ability to change the diameter of the laser beam; and
  - a moveable stage to which the board is coupled having the capability to adjust the position of the board with respect to the laser beam.
10. (Original) The hole drilling apparatus according to claim 9, wherein an angle of said mirror is adjustable for changing the laser beam passing position of said lens.
11. (New) The hole drilling apparatus of claim 9, wherein the means for positioning said hole on said board is maskless.